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REMARKS

Claims 1-7 are pending. Claim 4 has been amended. Claims 13-15 have been cancelled. No new matter has been added. Attached hereto is a marked-up version of the changes made to the claims by the current amendment, which includes the text of claims unchanged by this amendment for the Examiner's reference. The first page of the marked-up version is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE"..

Applicants appreciate the Examiner's indication of allowable subject matter in the most recent office action. In order to expedite issuance of the claims already indicated as allowable, non-allowed claims 13-15 have been canceled without prejudice to filing of a continuation application directed thereto.

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested. If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at (650) 326-2400 x5423.

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Unchanged) A small footprint semiconductor device package comprising:
a plastic package body for enclosing a die, the plastic package body including a top coupled to a bottom through a plurality of sides;
a lead including an enclosed portion by the package body and in electrical communication with the die, and an exposed portion of the lead extending from the side of the package body, folding back along the side of the package toward the bottom of the package at a first angle, and folding toward a center of the bottom of the package to form a lead foot, whereupon the portion of the lead along the side of the package and the portion of the lead along the bottom of the package form an angle of less than 90° from each other and the lead foot being inclined at a second angle relative to an underlying planar PC board to promote solder wetting.
2. (Unchanged) The package of claim 1 wherein the die is one of a power device, a discrete device, and an integrated circuit.
3. (Unchanged) The package of claim 1 wherein the lead forms a reverse gull wing shape.
4. (Amended) The package of claim 1 wherein the package has a reduced package profile including the lead.[.]
5. (Unchanged) The package of claim 1 wherein the lead foot is inclined at the second angle between 1° and 7° relative to the planar PC board.
6. (Unchanged) The package of claim 1 wherein the package body further comprises a notch configured to receive a portion of the lead foot, thereby

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permitting the lead foot to be partially recessed within the package body in order to reduce a height of the package.

7. (Unchanged) The package of claim 1 wherein the notch includes a depth of about two-thirds a thickness of the lead .

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